

149745

SEARCH REQUEST FORM Scientific and Technical Information Center - EIC2800

Rev. 3/15/2004 This is an experimental format -- Please give suggestions or comments to Jeff Harrison, JEF-4B68, 272-2511.

Date <u>3/13/05</u>	Serial # <u>101644, 890</u>	Priority Application Date <u>3/6/02</u>
Your Name <u>Jeff Harrison</u>	Examiner # <u>73172</u>	
AU <u>US</u>	Phone <u>979-1838</u>	Room <u>JA36</u>
In what format would you like your results? Paper is the default.		
<input checked="" type="radio"/> PAPER <input type="radio"/> DISK <input type="radio"/> EMAIL		

If submitting more than one search, please prioritize in order of need.

Need before
4/12

The EIC searcher normally will contact you before beginning a prior art search. If you would like to sit with a searcher for an interactive search, please notify one of the searchers.

Where have you searched so far on this case?

Circle: USPT DWPI EPO Abs JPO Abs IBM TDB

Other: _____

What relevant art have you found so far? Please attach pertinent citations or Information Disclosure Statements.

What types of references would you like? Please checkmark:

Primary Refs Nonpatent Literature _____ Other _____
Secondary Refs Foreign Patents _____
Teaching Refs _____

What is the topic, such as the novelty, motivation, utility, or other specific facets defining the desired focus of this search? Please include the concepts, synonyms, keywords, acronyms, registry numbers, definitions, structures, strategies, and anything else that helps to describe the topic. Please attach a copy of the abstract and pertinent claims.

Claims 153-188

Problem See pages 2-3

Solution 11 11 3-7

- Semiconductor Component
- Thinned Encapsulated polymer layers
-- on six sides

Staff Use Only

Searcher: Harrison

Searcher Phone: 22511

Searcher Location: STIC-EIC2800, JEP-4B68

Date Searcher Picked Up: 4-13-05

Date Completed: 4-14-05

Searcher Prep/Rev Time: 92

Online Time: 86

Type of Search

Structure (#) _____

Bibliographic

Litigation _____

Fulltext _____

Patent Family _____

Other _____

Vendors

STN

Dialog

Questel/Orbit _____

Lexis-Nexis _____

WWW/Internet _____

Other _____

SYSTEM:OS - DIALOG OneSearch

File 2:INSPEC 1969-2005/Apr W1
 File 6:NTIS 1964-2005/Apr W1
 File 8:Ei Compendex(R) 1970-2005/Apr W1
 File 25:Weldasearch-19662005/Feb (c) 2005 TWI Ltd
 File 31:World Surface Coatings Abs 1976-2005/Mar
 File 34:SciSearch(R) Cited Ref Sci 1990-2005/Apr W1
 File 35:Dissertation Abs Online 1861-2005/Mar
 File 36:MetalBase 1965-20050105
 File 63:Transport Res(TRIS) 1970-2005/
 File 65:Inside Conferences 1993-2005/Apr W2
 File 81:MIRA - Motor Industry Research 2001-2005/Feb
 File 87:TULSA (Petroleum Abs) 1965-2005/Apr W2
 File 94:JICST-EPlus 1985-2005/Feb W4
 File 95:TEME-Technology & Management 1989-2005/Mar W1
 File 96:FLUIDEX 1972-2005/Apr
 File 99:Wilson Appl. Sci & Tech Abs 1983-2005/Mar
 File 103:Energy SciTec 1974-2005/Mar B2
 File 104:AeroBase 1999-2005/Jan
 File 118:ICONDA-Intl Construction 1976-2005/Mar
 File 144:Pascal 1973-2005/Apr W1
 File 239:Mathsci 1940-2005/May
 File 240:PAPERCHEM 1967-2005/Apr W1
 File 248:PIRA 1975-2005/Mar W4
 File 315:ChemEng & Biotec Abs 1970-2005/Mar
 File 323:RAPRA Rubber & Plastics 1972-2005/Mar
 File 434:SciSearch(R) Cited Ref Sci 1974-1989/Dec
 File 350:Derwent WPIX 1963-2005/UD,UM &UP=200523
 File 347:JAPIO Nov 1976-2004/Dec(Updated 050405)
 File 344:Chinese Patents Abs Aug 1985-2004/May

Set	Items	Description
S1	6135	THINN??????(3N) (SEMICOND????????? OR SUBSTRATE?? OR SURFACE-???)
S2	1827	THINN??????(8N) SEMICOND?????????
S3	11897	THINN??????(8N) (SIDE OR SIDES OR BACKSIDE?? OR SURFACE OR -SURFACES)
S4	4219	THINN??????(8N) SUBSTRATE??
S5	64	1AND2AND3AND4
S6	4908	THINN??????(10N) (EDG???? OR PERIPH???????)
S7	6	5AND6
S8	6141	THINN??????(10N) (ENCAPSULAT????? OR POLYMER????? OR RESIN?-???? OR SEAL????? OR HERMETIC????)
S9	4	5AND8
S10	7179	THINN??????(120N) (DIE OR DIES OR DICE OR WAFER???????)
S11	18	5AND10
S12	3	5AND8AND10
S13	21	S7 OR S9 OR S11 OR S12
S14	21	RD S13 (unique items)
S15	1	S14 AND ENCAPSUL?????????/TI,AB,DE,ID
S16	7	S14 AND (RESIN????? OR POLYMER????? OR PARYLEN? OR EPOX???-?) /TI,AB,DE,ID
S17	7	S15:S16
S18	10	S14 AND THINN??????/TI
S19	7	S18 NOT S17
S20	5444	THIN??????(1N) (DIE OR DIES OR DICE OR WAFER???????)
S21	11	S14 AND S20
S22	3	S21 NOT (S18 OR S17)

13apr05 16:36:37 User259284 Session D3149.2

File 2:INSPEC 1969-2005/Apr W1
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Set	Items	Description
S1	873	(ENCAPSULA????????? OR ENVELOP?????????) (5N) (WAFER????? OR DIE OR DIES OR MICROCHIP?????? OR DICE OR CHIP????)
S2	575	(ENCAPSULA????????? OR ENVELOP?????????) (4N) (RESIN????? OR POLYMER???????)
S3	66	1AND2
S4	2	S3 AND LAYERS
S5	13	S3 AND FILMS
S6	9	S3 AND TWO
S7	1	S3 AND SECOND
S8	2	S3 AND ANOTHER
S9	1	S3 AND DOUBLE
S10	2	S3 AND (BI OR DI)
S11	0	S3 AND (BILAYER? OR DILAYER?)
S12	0	S3 AND EDGES
S13	1	S3 AND EDGE
S14	0	S3 AND PERIPH?
S15	27	S4:S13
S16	2	S15/2002-2005
S17	25	S15 NOT S16
S18	12	S17 AND (TEST????????? OR PROTECT????????? OR BURN????????? OR INSPECT????????? OR DAMAG???????)
S19	4	DENS?????? AND S3
S20	492	PARYLEN?
S21	0	S3 AND S20
S22	6	S1:S2 AND PARYLEN?
S23	10	S19 OR S22
S24	10	S23 NOT S18
S25	1	S24/2003-2005
S26	9	S24 NOT S25

CAS/STN FILE 'WPIX, HCAPLUS' ENTERED AT 14:20:26 ON 13 APR 2005

L1 216 S FARNWORTH?/IN AND WOOD A?/IN
L2 9 S L1 AND DOAN T?/IN
L3 9 S L2 AND (THIN##### OR ENCAP##### OR DIE)
L4 SEL PLU=ON L3 1- IC RN : 19 TERMS
L5 227186 S L4
L6 9 S L3 AND L5
L7 9 S L2
L8 SEL PLU=ON L7 1- IC MC FTERM NCL : 54 TERMS
L9 4488 S THINN#####(2A) (DIE OR WAFER OR SEMICOND##### OR SUBSTRATE OR BACK OR BACKSIDE OR SIDE OR CHIP
OR MICROCHIP)
L10 74574 S (ENCAPSULAT##### OR COVER##### OR PROTECT#####) (3A) (EDGES OR PERIPHER##### OR FULL## OR
TOTAL## OR COMPLET#####)
L11 111322 S (DOUBLE OR ANOTHER OR BOTH OR PAIR#####) (3A) (?POLYMER? OR ?PLASTIC? OR ?THERMOSET? OR ?RESIN?
OR RUBBER? OR ELASTOMER? OR PARYLENE?)
L12 581934 S (TWO OR 2 OR SECOND OR 2ND) (3A) (?POLYMER? OR ?PLASTIC? OR ?THERMOSET? OR ?RESIN? OR RUBBER? OR
ELASTOMER? OR PARYLENE? OR EPOX##### OR POLYIMID##### OR POLYAMID##### OR AMID## OR IMID##### OR ?SILICONE?)
L13 11732 S (DOUBLE OR ANOTHER OR BOTH OR PAIR#####) (3A) (EPOX##### OR POLYIMID##### OR POLYAMID##### OR
AMID##### OR IMID##### OR ?SILICONE?)
L14 12925 S (ORGANIC##### OR ORG) (4A) (ENCAPSUL##### OR SEAL##### OR HERMETIC##### OR PROTECT#####)
L15 148 S L9 AND (L10 OR L11 OR L12 OR L13 OR L14)
L16 459450 S L8
L17 767 S L16 AND L9
L18 18297 S L16 AND (L10 OR L11 OR L12 OR L13 OR L14)
L19 19142 S L15 OR L17 OR L18
L20 1032 S L19 AND THINN#####
L21 2104 S L19 AND (WAFER OR DIE)
L22 429 S L20 AND L21
L23 2 S L22 AND 25722-33-2
L24 0 S L22 AND DEXTER
L25 14 S (L9 OR L10 OR L11 OR L12 OR L13 OR L14 OR L15 OR L16 OR L17 OR L18) AND DEXTER
L26 53 S (L9 OR L10 OR L11 OR L12 OR L13 OR L14 OR L15 OR L16 OR L17 OR L18) AND HYSOL
L27 52 S (L9 OR L10 OR L11 OR L12 OR L13 OR L14 OR L15 OR L16 OR L17 OR L18) AND (FP4450 OR 4450)
L28 2 S (L9 OR L10 OR L11 OR L12 OR L13 OR L14 OR L15 OR L16 OR L17 OR L18) AND VPES
L29 102 S (L23 OR L24 OR L25 OR L26 OR L27 OR L28) AND (L10 OR L11 OR L12 OR L13)
L30 7 S L29 AND (VIA OR PIN OR PINN##### OR EDG##(2A) (CONTACT##### OR CONNECT##### OR
INTERCONNECT#####) OR REVERS##(2A) BIAS##)
L31 0 S L29 AND (?PARYLENE? OR 25722-33-2)
L32 9 S (L22 OR L23 OR L24 OR L25 OR L26 OR L27 OR L28 OR L29) AND (?PARYLENE? OR 25722-33-2)
L33 2 S L26 AND L27
L34 33 S L23 OR L25 OR L28 OR L30 OR L32 OR L33
L35 SEL PLU=ON L34 1- IC RN : 152 TERMS

10/646,897

FILE 'LCA' ENTERED AT 15:30:11 ON 13 APR 2005

L36 7724 S L35
L37 65 S L36 AND (SEAL##### OR ENCAPS##### OR HERMETIC#####)
L38 SEL PLU=ON L37 1- RN : 248 TERMS

FILE 'WPIX, JAPIO, HCAPLUS' ENTERED AT 15:31:25 ON 13 APR 2005

L39 SEL PLU=ON L34 1- PRN : 29 TERMS

FILE 'HCAPLUS' ENTERED AT 15:37:24 ON 13 APR 2005

L40 20 S L39
L41 3 S L40 AND THINN#####
L42 SEL PLU=ON L41 1- RN : 3 TERMS
L43 37065 S L42
L44 2 S L41 AND L43
L45 1 S L41 NOT L44

FILE 'JARIO' ENTERED AT 15:39:03 ON 13 APR 2005

L46 3 S L39
L47 2 S L46 AND THIN#####
L48 3 S (L46 OR L47)

FILE 'HCAPLUS, JARIO' ENTERED AT 15:41:03 ON 13 APR 2005

L49 58 S THINN##### AND (SECOND OR 2ND) (W) (POLYMER##### OR RESIN##### OR ENCAPSU##### OR SEALANT)
L50 7 S L49 AND (PIN OR PINN##### OR VIA OR CONTACT#####)
L51 5 S ("FABIANOWSKI W, 1995, V5, P199, ADV MATER OPT ELECTRON"/RE OR "FABIANOWSKI W, 1995, V5, P199,
ADVANCED MATERIALS FOR OPTICS AND ELECTRONICS"/RE)
L52 0 S L51 AND THIN#####
L53 SEL PLU=ON L51 1- RN : 16 TERMS
L54 1951077 S L53
L55 5 S L51 AND L54
L56 55 S (6 OR SIX)(W)SIDES
L57 0 S L56 AND (L5 OR L16)
L58 2 S L56 AND SEMICOND#####

10/646,897

FILE 'WPIX, JAPIO' ENTERED AT 15:45:42 ON 13 APR 2005
L59 579 S (6 OR SIX) (W) SIDES
L60 14 S L59 AND SEMICOND#####
L61 40 S L59 AND (WAFER OR DIE)
L62 0 S L59 AND (WAFER AND DIE)
L63 18 S L59 AND ?POLYMER?
L64 8 S L3
L65 SEL PLU=ON L64 1- PLE : 50 TERMS
L66 722011 S L65
L67 11 S L59 AND L66
L68 4 S L60 AND L61
L69 0 S L60 AND L63
L70 2 S L61 AND L63
L71 69 S L60 OR L61 OR L63 OR (L67 OR L68 OR L69 OR L70)
L72 4 S L71 AND (BACK##### OR REAR)
L73 1 S L71 AND ENCAPSUL#####
L74 5 S L59 AND ENCAPSUL#####
L75 4 S (L73 OR L74) NOT L72
L76 2 S L59 AND ENVELOP#####
L77 1 S L76 NOT (L72 OR L75)
L78 4293 S (ENVELOP##### OR ENCAPSULAT#####) (4A) (WAFER OR DIE OR CHIP OR MICROCHIP OR SUBSTRATE)
L79 4553 S L78 OR ENCAPSULA##### (4A) (WAFER OR DIE OR CHIP OR MICROCHIP OR SUBSTRATE)
L80 785 S L79 AND (EDG### OR PERIPHER#####)
L81 68 S L80 AND LAYERS
L82 23 S L80 AND FILMS
L83 190 S L80 AND (POLYMERS OR RESINS OR COPOLYMERS OR MONOMERS OR HOMOPOLYMERS OR PLASTICS OR THERNOPLASTIC? OR THERMOSET? OR ELASTOMER? OR RUBBER##)
L84 37 S (L81 OR L82) AND L83
L85 41 S (L81 OR L82) AND SEMICOND#####
L86 110 S L83 AND SEMICOND#####
L87 18 S L84 AND L85 AND L86
L88 777 S (L78 OR L79 OR L80 OR L81 OR L82 OR L83 OR L84 OR L85 OR L86 OR L87) AND ENVELOP#####
L89 0 S L71 AND ENVELOP#####
L90 210 S (L71 OR (L78 OR L79 OR L80 OR L81 OR L82 OR L83 OR L84 OR L85 OR L86 OR L87)) AND TEST#####
L91 573 S (L71 OR (L78 OR L79 OR L80 OR L81 OR L82 OR L83 OR L84 OR L85 OR L86 OR L87)) AND PROTECT#####
L92 9 S (L71 OR (L78 OR L79 OR L80 OR L81 OR L82 OR L83 OR L84 OR L85 OR L86 OR L87)) AND PHOTOPOLYM?
L93 36 S (L71 OR (L78 OR L79 OR L80 OR L81 OR L82 OR L83 OR L84 OR L85 OR L86 OR L87)) AND PHOTOSENS?
L94 98 S (L71 OR (L78 OR L79 OR L80 OR L81 OR L82 OR L83 OR L84 OR L85 OR L86 OR L87)) AND SENSITIVE
L95 533 S (L71 OR (L78 OR L79 OR L80 OR L81 OR L82 OR L83 OR L84 OR L85 OR L86 OR L87)) AND RESIST#####
L96 5 S (L71 OR (L78 OR L79 OR L80 OR L81 OR L82 OR L83 OR L84 OR L85 OR L86 OR L87)) AND STEREO#####
L97 333 S (L71 OR (L78 OR L79 OR L80 OR L81 OR L82 OR L83 OR L84 OR L85 OR L86 OR L87)) AND ?TAPE?
L98 556 S (L71 OR (L78 OR L79 OR L80 OR L81 OR L82 OR L83 OR L84 OR L85 OR L86 OR L87)) AND ?BALL?
L99 312 S (L71 OR (L78 OR L79 OR L80 OR L81 OR L82 OR L83 OR L84 OR L85 OR L86 OR L87)) AND ?BUMP?
L100 1 S (L71 OR (L78 OR L79 OR L80 OR L81 OR L82 OR L83 OR L84 OR L85 OR L86 OR L87)) AND REVERS##### (5A) BIAS###
L101 13 S (L71 OR (L78 OR L79 OR L80 OR L81 OR L82 OR L83 OR L84 OR L85 OR L86 OR L87)) AND PARYLEN?
L102 26 S L72 OR L75 OR L87
L103 280 S (L90 OR L91 OR L92 OR L93 OR L94 OR L95 OR L96 OR L97 OR L98 OR L99 OR L100 OR L101) AND (LAYERS OR FILMS OR COATS OR COATINGS OR SUBLAYERS OR SUBCOAT?)
L104 354 S (L90 OR L91 OR L92 OR L93 OR L94 OR L95 OR L96 OR L97 OR L98 OR L99 OR L100 OR L101) AND POLYMERS
L105 634 S (L90 OR L91 OR L92 OR L93 OR L94 OR L95 OR L96 OR L97 OR L98 OR L99 OR L100 OR L101) AND (CONTACTS OR PINS OR VIAS OR BALLS OR BUMPS OR BALLGRIDS OR ARRAYS OR DENSE#####)
L106 81 S L103 AND L104
L107 80 S L103 AND L105
L108 35 S L103 AND L104 AND L105
L109 27 S L108 NOT L102
L110 20 S L109 AND (CONTACT OR VIA)
L111 81 S L66 AND (L106 OR L107 OR L108)
L112 46 S L110 OR L102
L113 57 S L111 NOT L112
L114 5 S L113 AND PARYLEN?
L115 15 S L113 AND (SIDES OR EDGES OR SURFACES)
L116 19 S (L114 OR L115)
L117 5 S TEST##### AND L113
L118 4 S L117 NOT (L112 OR L116)

FILE 'SCISEARCH' ENTERED AT 16:13:19 ON 13 APR 2005

L119 6 S "FABIANOWSKI W, 1995, V5, P199, ADV MATER OPT ELECTR"/RE
L120 0 S L119 AND SIDES

26apr05 15:49:57 User259284 Session D3162.2
File 2:INSPEC 1969-2005/Apr W3

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Set	Items	Description
S1	118	STEREOIMAG? OR STEREOGRAPH????? (3N) IMAG???????
S2	1	S1 AND (PARYLEN? OR POLYMER? OR PHOTOPOLYMER? OR PHOTORESIST?)
S3	163	(NANO OR STEREO) (W) (LITHOG????????? OR PHOTOLITHOG?)
S4	2990	STEREOLITHOG????????? OR NANOLITHOG?
S5	13	STEREOPHOTOLITHOG????????? OR NANOPHOTOLITHOG?
S6	608	S3:S5 AND (PARYLEN????? OR POLYMER? OR RESIN?)
S7	50	S6 AND (STEREO?????????)
S8	50	S7 NOT S2
S9	4	S8 AND (NANOCIRCUIT? OR MICROCIRCUIT? OR CIRCUIT????? OR PC OR PCS OR PCB? ?)
S10	10	S8 AND (IC OR ICS OR VLSI OR ULSI OR SCALE() INTEGRAT?????- ???)
S11	14	S9:S10
S12	14	S11 NOT S2
S13	122500	CURING OR POLYMERS OR POLYMERISATION
S14	356	S1:S8 AND S13
S15	347	S14 NOT (S11 OR S2)
S16	19	S15 AND WAFER?
S17	1	S15 AND (PIN OR PINS)
S18	42	S15 AND THIN?????????
S19	48	S15 AND THICK?????????
S20	2	S15 AND (TAPE????? OR TAB)
S21	0	S15 AND UNDERFILL?
S22	2	S15 AND UNDERNEATH
S23	0	S15 AND UNDERSIDE
S24	29	S15 AND UNDER
S25	1	S16:S24 AND OPAQ?
S26	3975	ULTRAVIOLET LITHOGRAPHY (January 1999)
S27	26	S16:S24 AND S26
S28	25	S27 NOT (S25 OR S12 OR S2)
S29	3	S28 AND LAYERS
S30	12	S28 AND FILMS
S31	2	S28 AND COATINGS
S32	0	S28 AND COATS
S33	1	S28 AND MULTILAYER?
S34	0	S28 AND MULTI() LAYER?
S35	0	S28 AND MULTIPLE() LAYER?
S36	14	S29:S35

26apr05 16:01:37 User259284 Session D3162.3

SYSTEM:OS - DIALOG OneSearch

File 2:INSPEC 1969-2005/Apr W3
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File 6:NTIS 1964-2005/Apr W3

File 8:Ei Compendex(R) 1970-2005/Apr W3

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File 347:JAPIO Nov 1976-2004/Dec(Updated 050405)
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File 344:Chinese Patents Abs Aug 1985-2004/May
 (c) 2004 European Patent Office

File 371:French Patents 1961-2002/BOPI 200209
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Set	Items	Description
S1	3152	PARYLEN?
S2	21	S1 AND THINN???????????
S3	19	RD S2 (unique items)
S4	24	S1 AND OPAQ?
S5	16	RD S4 (unique items)
S6	16	S5 NOT S3

----- 4/27/05 -----

FILE 'INSPEC, WPIX, HCPLUS, JAPIO, JICST-EPLUS, COMPENDEX, PASCAL, METADEX, CERAB' ENTERED AT 17:00:21 ON 27 APR 2005

FILE 'INSPEC, WPIX, HCPLUS, JAPIO, JICST-EPLUS, COMPENDEX, PASCAL, METADEX, CERAB, DISSABS' ENTERED AT 17:00:35 ON 27 APR 2005

L1 1734 SEA ABB=ON PLU=ON PIN(4A) TERMIN#####(5A) CONTACT#####
L2 4167 SEA ABB=ON PLU=ON REVERS#####(5A) BIAS#####(6A) (HETEROJUNCTION
? OR HOMOJUNCTION? OR JUNCTION? OR PN OR NP OR NPN OR PNP)
L3 0 SEA ABB=ON PLU=ON L1 AND L2
L4 0 SEA ABB=ON PLU=ON (L1 OR L2) AND PHOTOPOLYMER#####
L5 1 SEA ABB=ON PLU=ON (L1 OR L2) AND PARYLENE?
D TI
D ALL
L6 1 SEA ABB=ON PLU=ON (L1 OR L2) AND 25722-33-2
L7 223 SEA ABB=ON PLU=ON (L1 OR L2) AND (ORGANIC OR PLASTIC? OR
THERMOPLASTIC? OR THERMOSET? OR RESIN##### OR POLYMER? OR
COPOLYMER? OR HOMOPOLYMER? OR MONOMER?)
L8 6 SEA ABB=ON PLU=ON L7 AND DIE
L9 24 SEA ABB=ON PLU=ON L7 AND LAYERS
L10 13 SEA ABB=ON PLU=ON L7 AND FILMS
L11 4 SEA ABB=ON PLU=ON L7 AND ENCAPSUL#####
L12 30 SEA ABB=ON PLU=ON (L1 OR L2) AND (ORGANIC OR PLASTIC? OR
THERMOPLASTIC? OR THERMOSET? OR RESIN##### OR POLYMER? OR
COPOLYMER? OR HOMOPOLYMER? OR MONOMER?) (4A) (LAYER OR FILM)

FILE 'STNGUIDE' ENTERED AT 17:12:21 ON 27 APR 2005

FILE 'WPIX' ENTERED AT 17:13:01 ON 27 APR 2005
E 1988-335756/AN

L13 1 SEA ABB=ON PLU=ON 88-335756/AN
D MAX

FILE 'DPCI' ENTERED AT 17:13:51 ON 27 APR 2005
E JP 63250482/PN

L14 1 SEA ABB=ON PLU=ON JP63250482/PN
D ALL

FILE 'STNGUIDE' ENTERED AT 17:14:51 ON 27 APR 2005

FILE 'DPCI' ENTERED AT 17:16:22 ON 27 APR 2005
E JP 63250482/PN.D

L15 2 SEA ABB=ON PLU=ON JP63250482/PN.D
D ALL TOT

FILE 'STNGUIDE' ENTERED AT 17:16:36 ON 27 APR 2005

FILE 'INSPEC, WPIX, HCPLUS, JAPIO, JICST-EPLUS, COMPENDEX, PASCAL, METADEX, CERAB, DISSABS' ENTERED AT 17:20:36 ON 27 APR 2005

L16 60 SEA ABB=ON PLU=ON (L8 OR L9 OR L10 OR L11 OR L12)
L17 47 DUP REM L16 (13 DUPLICATES REMOVED)
L18 15 SEA ABB=ON PLU=ON L17 AND THIN#####
L19 6 SEA ABB=ON PLU=ON L17 AND SIDES
L20 21 SEA ABB=ON PLU=ON (L18 OR L19)
D TI 1-21
D ALL 1-7 14-21
D MAX 8-13
L21 10 SEA ABB=ON PLU=ON L8 OR L11
L22 10 DUP REM L21 (0 DUPLICATES REMOVED)
L23 7 SEA ABB=ON PLU=ON L22 NOT L20

----- 4/26/05 10/646,897 -----

FILE 'WPIX, HCAPLUS' ENTERED AT 14:36:47 ON 26 APR 2005
L1 1 S US6717245/PN
L2 SEL L1 1- PN : 1 TERM

FILE 'DPCI' ENTERED AT 14:36:59 ON 26 APR 2005
L3 0 S US6717245/PN.D
L4 27 S US6717245/PN.G
L5 SEL L4 1- PN : 78 TERMS
L6 627 S L5/PN.D

FILE 'WPIX, HCAPLUS' ENTERED AT 14:39:36 ON 26 APR 2005
L7 SEL L1 1- IC : 1 TERM

FILE 'DPCI' ENTERED AT 14:39:51 ON 26 APR 2005
L8 4063 S L7
L9 73 S L6 AND L8
L10 8 S L6 AND SIDES
L11 0 S L6 AND ENVELOP?
L12 0 S L6 AND THINN#####
L13 89 S L6 AND DIE
L14 94 S L6 AND (RESIN##### OR ?POLYMER? OR SEAL##### OR ENCAPS#####
L15 96 S L6 AND (RESIN##### OR POLYMER? OR SEAL##### OR ENCAPS#####

=> s l13 and l14-15
L16 12 L13 AND (L14 OR L15)

=> s l9 and l13-14
L17 23 L9 AND (L13 OR L14)

=> s l9 and L15
L18 10 L9 AND L15

=> s l10 or l16-18
L19 40 L10 OR (L16 OR L17 OR L18)

=> sel prn

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L20 SEL L19 1- PRN : 66 TERMS

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L21 126 L20

=> s l21 and thinn#####
L22 3 L21 AND THINN#####

=> s l21 and envelop?
L23 0 L21 AND ENVELOP?

=> s l21 and encapsul?
L24 26 L21 AND ENCAPSUL?

----- 4/26/05 10/646,897 -----

=> s l21 and seal?
L25 28 L21 AND SEAL?

=> s l21 and complete?
L26 5 L21 AND COMPLETE?

=> s l21 and total?
L27 1 L21 AND TOTAL?

=> s l21 and surround?
L28 3 L21 AND SURROUND?

=> s l21 and entire?
L29 3 L21 AND ENTIRE?

=> s l21 and covered
L30 5 L21 AND COVERED

=> s l24-25 and bottom and top
L31 3 (L24 OR L25) AND BOTTOM AND TOP

=> s l24-25 and side
L32 19 (L24 OR L25) AND SIDE

=> s l22 or l26-32
L33 36 L22 OR (L26 OR L27 OR L28 OR L29 OR L30 OR L31 OR L32)